IPC ASSOCIATION CONNE ELECTRONICS INDUS	© Copyright 2005. II	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplier Info	rmation														
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*			
nsemi												2024-05-21			
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-Env-St	ewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorized Representative*				Title - Representative			Phone - Representative*				Email - Representative*				
Product-Env-St	ewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requ	ester Item Number	r Item Number Mfr Iter		em Number Mfr Item Name			Effective Dat	te Versi	e Version		Manufacturing Site		Weight* UOM	UOM	Unit Type
		NLSX4302EBMUTC Dual-Supp			ual-Supply Level Translator		2024-05-21					1.3	1.3367 mg		Each
Ianufacturii	ng Proccess Informat	ion						·						·	
Termi	nal Plating / Grid Array Ma	Plating / Grid Array Material		Terminal Base Alloy		SL Rating	Peak Process Body Temperatu		nre Max Time at Peak Temper		Temperatur	ature Number of Reflow Cycles		eles	
Precio Sn)	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy		1		260		C	30	seco		3		
Comments															
vel 1 - maximu	m time at peak temperatu	re during so	oldering is 10-3	0 seconds											
or more inform	nation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.125	mg	Supplier	Silicon (Si)	7440-21-3		0.125	mg
Die Attach Epoxy	0.0424	mg		Epoxy resin	proprietary data		0.0276	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0148	mg
Lead Frame	0.7011		Supplier	Tin (Sn)	7440-31-5		0.0018	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0015	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0018	mg
			Supplier	Copper (Cu)	7440-50-8		0.6961	mg
Mold Compound-Black	0.4394		Supplier	Epoxy and Phenolic Resin	40216-08-8		0.0352	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0022	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0088	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.3801	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0132	mg
Plating	0.0078	mg	Supplier	Silver (Ag)	7440-22-4		0.0006	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			В	Nickel (Ni)	7440-02-0		0.0068	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
Wire Bond - Au	0.021	mg	Supplier	Gold (Au)	7440-57-5		0.021	mg